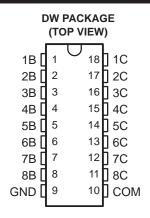
ULN2803A DARLINGTON TRANSISTOR ARRAY

SLRS049B - FEBRUARY1997 - REVISED OCTOBER 2003

- 500-mA Rated Collector Current (Single Output)
- High-Voltage Outputs . . . 50 V
- Output Clamp Diodes
- Inputs Compatible With Various Types of Logic
- Relay Driver Applications
- Compatible with ULN2800A Series

description/ordering information

The ULN2803A is a high-voltage, high-current Darlington transistor array. The device consists of eight npn Darlington pairs that feature high-voltage outputs with common-cathode clamp diodes for switching inductive loads. The collector-current rating of each Darlington pair is 500 mA. The Darlington pairs may be connected in parallel for higher current capability.



Applications include relay drivers, hammer drivers, lamp drivers, display drivers (LED and gas discharge), line drivers, and logic buffers. The ULN2803A has a 2.7-k Ω series base resistor for each Darlington pair for operation directly with TTL or 5-V CMOS devices.

ORDERING INFORMATION

	TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-	-40°C to 85°C	SOIC (DW)	Tube of 40	ULN2803ADW	ULN2803A	
	-40 C 10 85°C	SOIC (DW)	Reel of 2000	ULN2003ADWR	ULINZ603A	

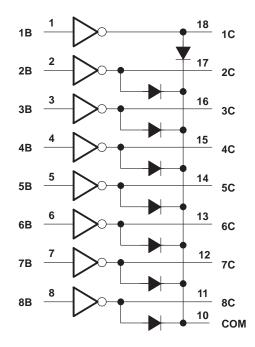
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



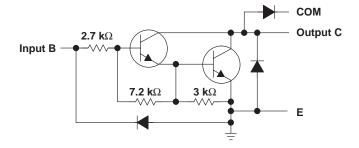
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logic diagram



schematic (each Darlington pair)



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absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)†

Collector-emitter voltage	50 V
Input voltage (see Note 1)	30 V
Continuous collector current	500 mA
Output clamp diode current	500 mA
Total substrate-terminal current	
Package thermal impedance, θ _{JA} (see Notes 2 and 3)	TBD°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, unless otherwise noted, are with respect to the emitter/substrate terminal GND.
 - 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics at 25°C free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
ICEX	Collector cutoff current	V _{CE} = 50 V, See Figure 1	I _I = 0,			50	μΑ
I _{I(off)}	Off-state input current	V _{CE} = 50 V, T _A = 70°C,	I _C = 500 μA, See Figure 2	50	65		μΑ
I _{I(on)}	Input current	$V_I = 3.85 V$,	See Figure 3		0.93	1.35	mA
	On-state input voltage	., .,	$I_C = 200 \text{ mA}$			2.4	V
V _{I(on)}		V _{CE} = 2 V, See Figure 4	$I_C = 250 \text{ mA}$			2.7	
, ,			$I_C = 300 \text{ mA}$			3	
		I _I = 250 μA, See Figure 5	$I_C = 100 \text{ mA},$		0.9	1.1	
V _{CE(sat)}	sat) Collector-emitter saturation voltage	I _I = 350 μA, See Figure 5	I _C = 200 mA,		1	1.3	٧
		I _I = 500 μA, See Figure 5	$I_C = 350 \text{ mA},$		1.3	1.6	
I _R	Clamp diode reverse current	$V_R = 50 V$,	See Figure 6	_		50	μΑ
٧F	Clamp diode forward voltage	$I_F = 350 \text{ mA},$	See Figure 7		1.7	2	V
Ci	Input capacitance	$V_I = 0 V$,	f = 1 MHz		15	25	pF

switching characteristics at 25°C free-air temperature

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, low- to high-level output	$V_{S} = 50 \text{ V},$	R _L = 163 Ω,		130		
^t PHL	Propagation delay time, high- to low-level output	$C_L = 15 pF$,	See Figure 8		20		ns
VOH	High-level output voltage after switching	V _S = 50 V, See Figure 9	$I_O \approx 300 \text{ mA},$	V _S -20		·	mV



PARAMETER MEASUREMENT INFORMATION

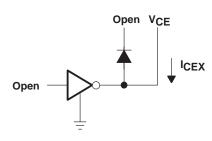


Figure 1. I_{CEX} Test Circuit

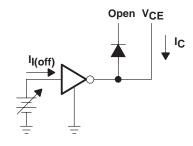


Figure 2. I_{I(off)} Test Circuit

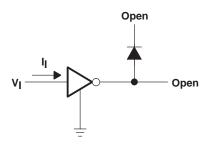


Figure 3. I_{I(on)} Test Circuit

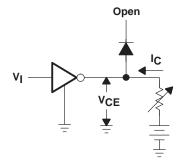


Figure 4. V_{I(on)} Test Circuit

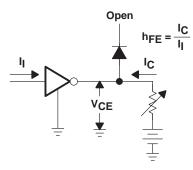


Figure 5. h_{FE} , $V_{CE(sat)}$ Test Circuit

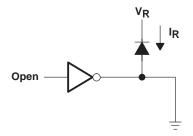


Figure 6. I_R Test Circuit

PARAMETER MEASUREMENT INFORMATION

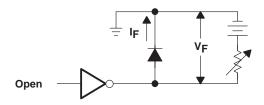
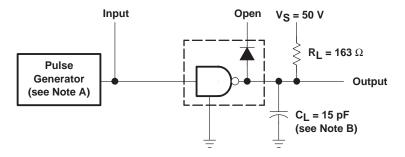
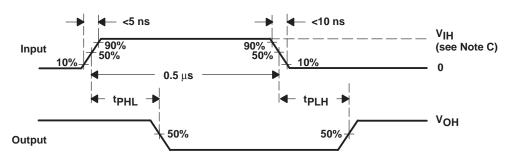


Figure 7. V_F Test Circuit



Test Circuit



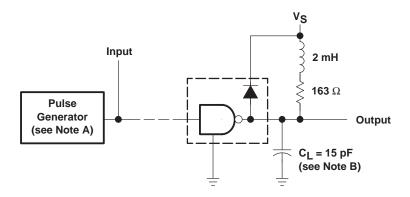
Voltage Waveforms

NOTES: A. The pulse generator has the following characteristics: PRR = 1 MHz, Z_O = 50 Ω . B. C_L includes probe and jig capacitance.

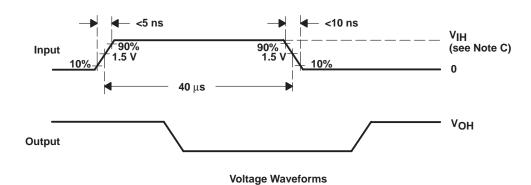
- C. V_{IH} = 3 V

Figure 8. Propagation Delay Times

PARAMETER MEASUREMENT INFORMATION



Test Circuit



NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 KHz, Z_O = 50 Ω .

- B. C_L includes probe and jig capacitance. C. V_{IH} = 3 V

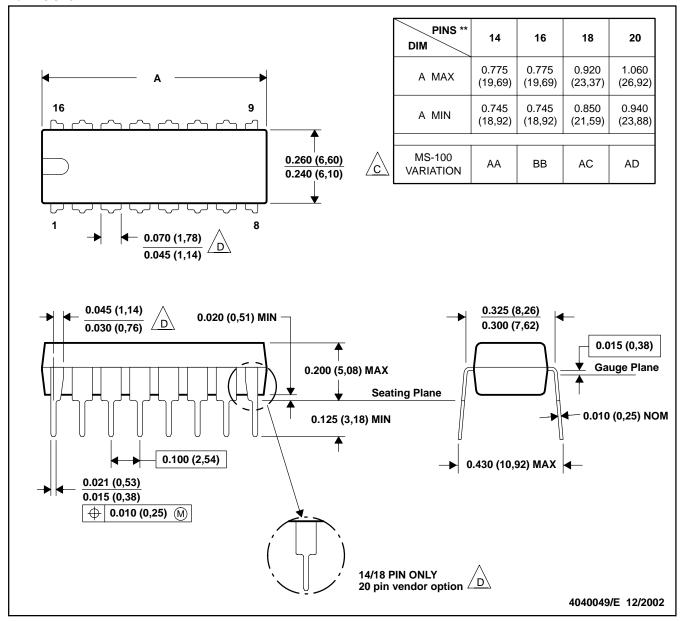
Figure 9. Latch-Up Test



N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

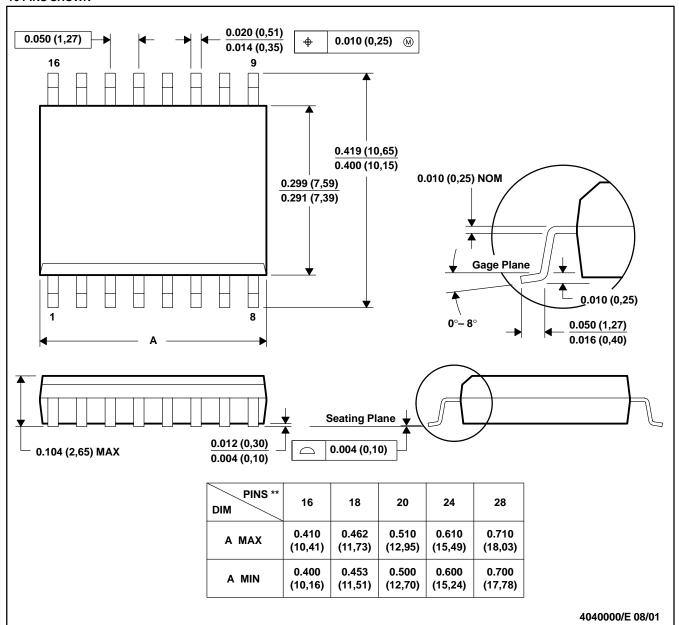
Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

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